

AMENDMENT UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE-  
EXAMINING GROUP 3652

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Yoo, Woo Sik  
Assignee: WaferMasters, Inc.  
Title: Wafer Transport System and Method  
Serial No.: 09/838,083 Filing Date: April 19, 2001  
Examiner: Charles A. Fox Group Art Unit: 3652  
Docket No.: M-11439 US

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Irvine, California  
November 22, 2002

**GROUP 3600**

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action dated September 24, 2002, Applicants submit the following amendments and remarks.

IN THE CLAIMS

The following is a clean version of the entire set of pending claims. In accordance with 37 C.F.R. §1.121(c)(1)(ii), Attachment A provides a marked-up version of the claim containing the newly introduced changes.

1. (Amended) A method for transporting semiconductor wafers comprising:  
providing a processing system including a transport module and process chamber;  
extending a semiconductor wafer transport device from said transport module into an adjacently positioned Front Opening Unified Pod (FOUP) while said FOUP remains a separate component from said processing system; and  
removing at least one semiconductor wafer from said FOUP using said wafer transport device.